μ**ΡΑ2690T1**R

COMPLEMENTARY MOSFET 20V, 4.0A, $42m\Omega$ / -20V, -3.0A, $79m\Omega$

Description

The μ PA2690T1R is Dual N- and P-channel MOS Field Effect Transistors for switching application.

This device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

Features

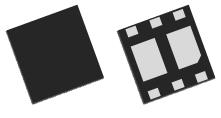
- N-channel 2.5V, P-channel 1.8V drive available
- Low on-state resistance N-channel

$-R_{DS(on)1} = 42 \text{ m}\Omega \text{ MAX.} (V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A})$

 $- R_{DS (on)1} = 42 \text{ III} 2 \text{ IVIAX.} (V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A})$ $- R_{DS (on)2} = 62 \text{ m}\Omega \text{ MAX.} (V_{GS} = 2.5 \text{ V}, I_D = 2.0 \text{ A})$

P-channel

- ---- $R_{DS (on)1} = 79 \text{ m}\Omega \text{ MAX.} (V_{GS} = -4.5 \text{ V}, I_D = -1.5 \text{ A})$
- ---- $R_{DS (on)2} = 105 \text{ m}\Omega \text{ MAX}. (V_{GS} = -2.5 \text{ V}, I_D = -1.5 \text{ A})$
- ---- $R_{DS (on)3} = 182 \text{ m}\Omega \text{ MAX.} (V_{GS} = -1.8 \text{ V}, I_D = -1.5 \text{ A})$
- Built-in gate protection diode
- Lead-free and Halogen-free



6pinHUSON2020(Dual)

Ordering Information

| Part Number | Package | | | |
|--------------------------------|---------------------|--|--|--|
| μPA2690T1R-E2-AX ^{*1} | 6pinHUSON2020(Dual) | | | |

Note: *1.Pb-free (This product does not contain Pb in the external electrode and other parts.)

Absolute Maximum Ratings (T_A = 25°C)

| Item | Symbol | N-CHANNEL | P-CHANNEL | Unit |
|--|-----------------------|-----------|------------|------|
| Drain to Source Voltage ($V_{GS} = 0 V$) | V _{DSS} | 20 | -20 | V |
| Gate to Source Voltage (V _{DS} = 0 V) | V _{GSS} | ±12 | ∓10 | V |
| Drain Current (DC) | I _{D(DC)} | ±4.0 | ∓3.0 | А |
| Drain Current (pulse) *1 | I _{D(pulse)} | ±16 | ∓12 | А |
| Total Power Dissipation (1 unit, 5 s) *2 | P _{T1} | 1 | W | |
| Total Power Dissipation (2 units, 5 s) *2 | P _{T2} | 2 | W | |
| Channel Temperature | T _{ch} | 15 | °C | |
| Storage Temperature | T _{STG} | –55 to | °C | |

Notes: ∗1. PW≤10 µs, Duty Cycle≤1%

*2. Mounted on glass epoxy board of 25.4mm x 25.4mm x 0.8mmt

Caution: This product (N-channel) is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

 $V_{ESD} = \pm 400V \text{ MIN.} (C = 100 \text{pF}, R = 1.5 \text{K}\Omega)$



R07DS1000EJ0101 Rev.1.01 Mar 04, 2013

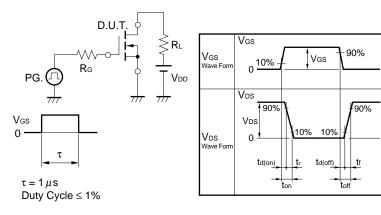
Electrical Characteristics (T_A = 25°C)

N-channel MOSFET

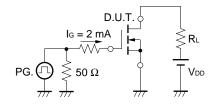
| Characteristics | Symbol | MIN. | TYP. | MAX. | Unit | Test Conditions |
|---------------------------------|----------------------|------|------|------|------|---|
| Zero Gate Voltage Drain Current | I _{DSS} | | | 1.0 | μA | V _{DS} = 20 V, V _{GS} = 0 V |
| Gate Leakage Current | I _{GSS} | | | ±10 | μA | V_{GS} = ±10 V, V_{DS} = 0 V |
| Gate Cut-off Voltage | V _{GS(off)} | 0.5 | | 1.5 | V | V_{DS} = 10 V, I_{D} = 1 mA |
| Forward Transfer Admittance *1 | y _{fs} | 5.0 | | | S | V _{DS} = 10 V, I _D = 2.0 A |
| Drain to Source On-state | R _{DS(on)1} | | 33 | 42 | mΩ | V_{GS} = 4.5 V, I _D = 2.0 A |
| Resistance * ¹ | R _{DS(on)2} | | 43 | 62 | mΩ | V_{GS} = 2.5 V, I _D = 2.0 A |
| Input Capacitance | C _{iss} | | 330 | | pF | V_{DS} = 10 V, V_{GS} = 0 V, |
| Output Capacitance | C _{oss} | | 66 | | pF | f = 1.0 MHz |
| Reverse Transfer Capacitance | C _{rss} | | 38 | | pF | |
| Turn-on Delay Time | t _{d (on)} | | 12 | | ns | I _D = 2.0 A, V _{DD} = 10 V, |
| Rise Time | tr | | 6.4 | | ns | V_{GS} = 4.5 V, R_{G} = 6 Ω |
| Turn-off Delay Time | t _{d (off)} | | 27 | | ns | |
| Fall Time | t _f | | 6.6 | | ns | |
| Total Gate Charge | Q _G | | 4.5 | | nC | $I_D = 4.0 \text{ A}$, $V_{DD} = 16 \text{ V}$, |
| Gate to Source Charge | Q _{GS} | | 1.0 | | nC | V _{GS} = 10 V |
| Gate to Drain Charge | Q _{GD} | | 1.5 | | nC | |
| Body Diode Forward Voltage *1 | V _{F(S-D)} | | | 1.5 | V | I_F = 4.0 A, V_{GS} = 0 V |

Note: *1. Pulsed

TEST CIRCUIT 1 SWITCHING TIME



TEST CIRCUIT 2 GATE CHARGE



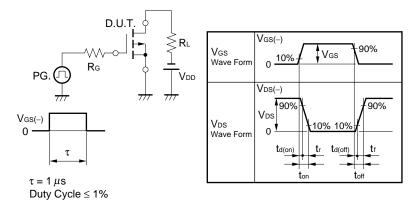


P-channel MOSFET

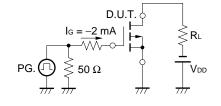
| Characteristics | Symbol | MIN. | TYP. | MAX. | Unit | Test Conditions | |
|---------------------------------|----------------------|------|------|------------|------|---|--|
| Zero Gate Voltage Drain Current | I _{DSS} | | | -1.0 | μA | V_{DS} = -20 V, V_{GS} = 0 V | |
| Gate Leakage Current | I _{GSS} | | | ∓10 | μA | $V_{GS} = \mp 8 V, V_{DS} = 0 V$ | |
| Gate Cut-off Voltage | V _{GS(off)} | -0.4 | | -1.1 | V | $V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$ | |
| Forward Transfer Admittance *1 | y _{fs} | 4.5 | | | S | $V_{DS} = -5 V$, $I_{D} = -2 A$ | |
| Drain to Source On-state | R _{DS(on)1} | | 63 | 79 | mΩ | V_{GS} = -4.5 V, I _D = -1.5 A | |
| Resistance *1 | R _{DS(on)2} | | 78 | 105 | mΩ | V_{GS} = -2.5 V, I _D = -1.5 A | |
| | R _{DS(on)3} | | 109 | 182 | mΩ | V_{GS} = -1.8 V, I _D = -1.5 A | |
| Input Capacitance | C _{iss} | | 473 | | pF | $V_{DS} = -10 V$, $V_{GS} = 0 V$, | |
| Output Capacitance | C _{oss} | | 88 | | pF | f = 1.0 MHz | |
| Reverse Transfer Capacitance | C _{rss} | | 68 | | pF | | |
| Turn-on Delay Time | t _{d (on)} | | 11.5 | | ns | $I_D = -1.5 \text{ A}, V_{DD} = -10.0 \text{ V},$ | |
| Rise Time | tr | | 4.0 | | ns | V_{GS} = -4.0 V, R_G = 6 Ω | |
| Turn-off Delay Time | t _{d (off)} | | 37.5 | | ns | | |
| Fall Time | t _f | | 12.5 | | ns | | |
| Total Gate Charge | Q _G | | 5.1 | | nC | $I_D = -3.0 \text{ A}$, $V_{DD} = -16 \text{ V}$, | |
| Gate to Source Charge | Q _{GS} | | 0.9 | | nC | V _{GS} = -4.5 V | |
| Gate to Drain Charge | Q _{GD} | | 1.5 | | nC | | |
| Body Diode Forward Voltage *1 | V _{F(S-D)} | | | 1.5 | V | I _F = 3.0 A, V _{GS} = 0 V | |

Note: *1. Pulsed

TEST CIRCUIT 1 SWITCHING TIME



TEST CIRCUIT 2 GATE CHARGE



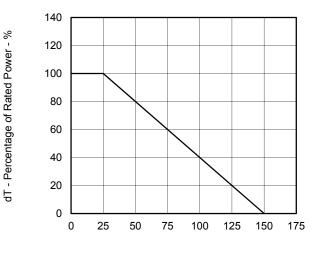


I_D – Drain Current - A

Typical Characteristics ($T_A = 25^{\circ}C$)

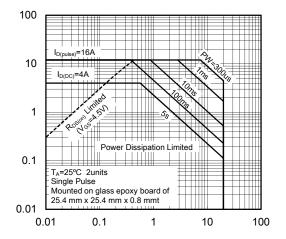
N-channel MOSFET

DERATING FACTOR OF FORWARD BIAS SAFE **OPERATING AREA**

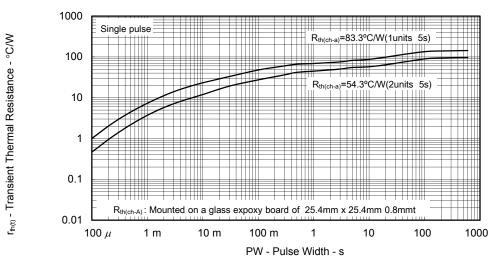


T_A -Ambient Temperature - °C



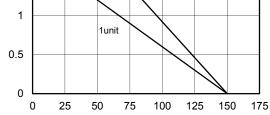






TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

2.5 Mounted on a glass expoxy board of 25.4mm x 25.4mm 0.8mmt P_{T} - Total Power Dissipation - W 2 PW=5sec 1.5 2units 1

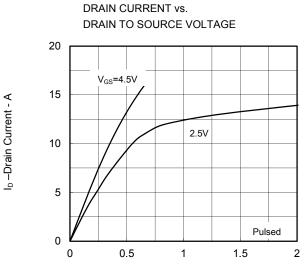


TOTAL POWER DISSIPATION vs.

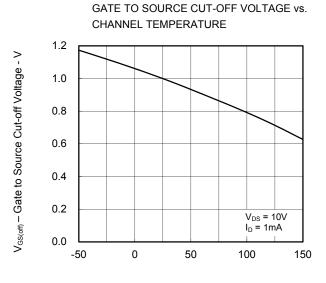
AMBIENT TEMPERATURE

T_A -Ambient Temperature - °C

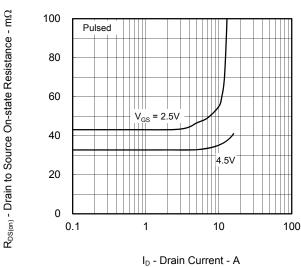






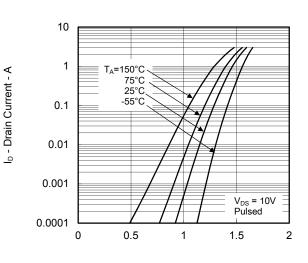


T_{ch} - Channel Temperature - °C



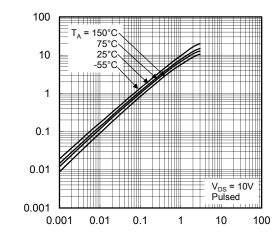
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

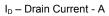
FORWARD TRANSFER CHARACTERISTICS

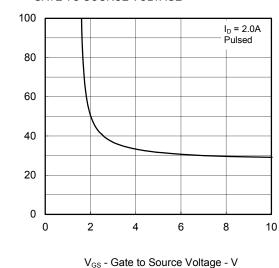


V_{GS} - Gate to Source Voltage - V

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT





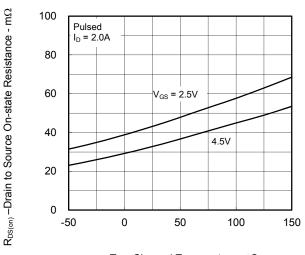


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



| y_{fs} | - Forward Transfer Admittance - S

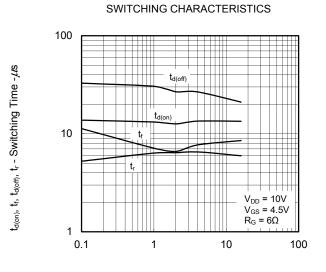
 $R_{\text{DS(on)}}$ – Drain to Source On-state Resistance - $m\Omega$

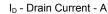


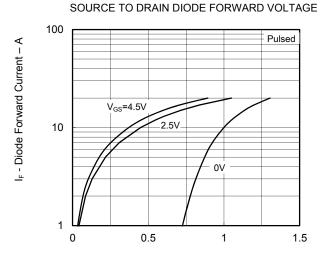
DRAIN TO SOURCE ON-STATE RESISTANCE vs.

CHANNEL TEMPERATURE

T_{ch} - Channel Temperature - °C

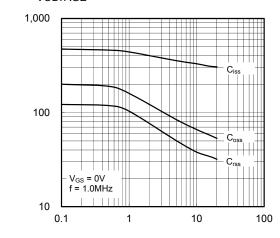






 $V_{F(S\!-\!D)}$ - Drain to Source Voltage - V

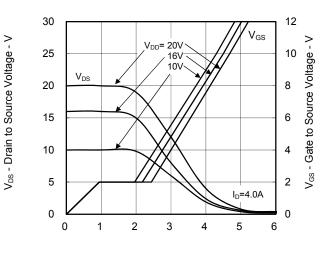
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



Ciss, Coss, Crss - Capacitance - pF

V_{DS} – Drain to Source Voltage - V

DYNAMIC INPUT/OUTPUT CHARACTERISTICS



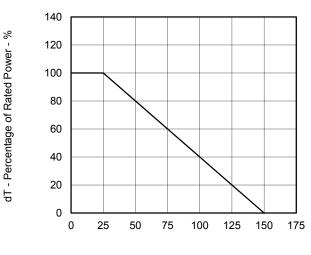
Q_G - Gate Charge - nC



I_D – Drain Current - A

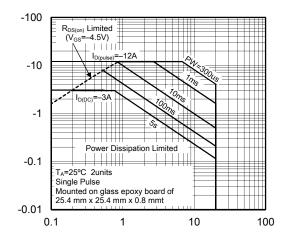
P-channel MOSFET

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

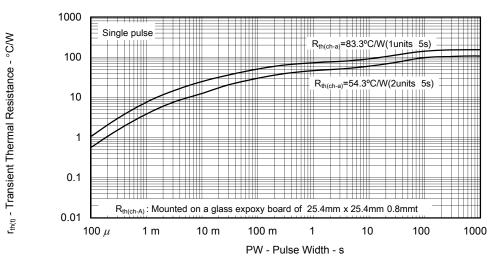


T_A -Ambient Temperature - °C





V_{DS} - Drain to Source Voltage - V



TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

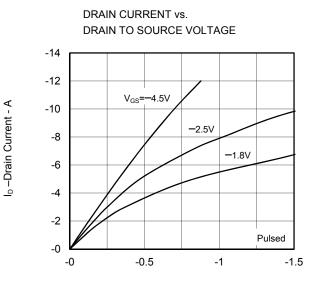
2.5 Mounted on a glass expoxy board of 25.4mm x 25.4mm 0.8mmt P_{T} - Total Power Dissipation - W PW=5sec 2 1.5 2units 1 1unit 0.5 0 25 0 50 75 100 125 150 175

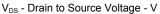
TOTAL POWER DISSIPATION vs.

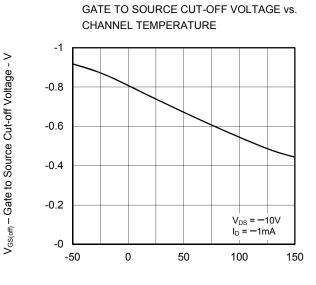
AMBIENT TEMPERATURE

T_A -Ambient Temperature - °C

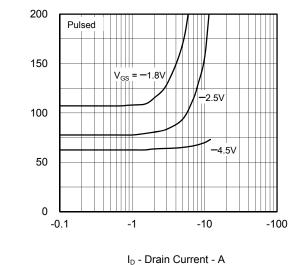






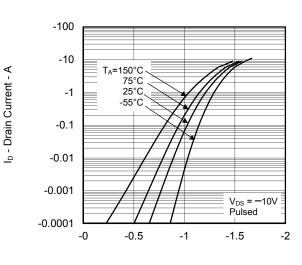


T_{ch} - Channel Temperature - °C



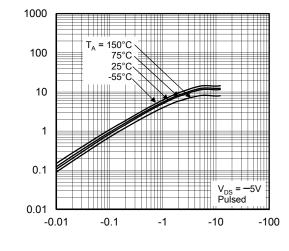
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

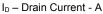
FORWARD TRANSFER CHARACTERISTICS

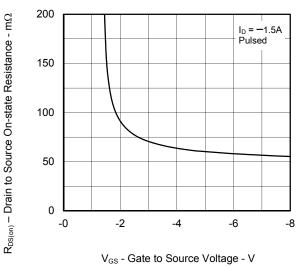


V_{GS} - Gate to Source Voltage - V

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT





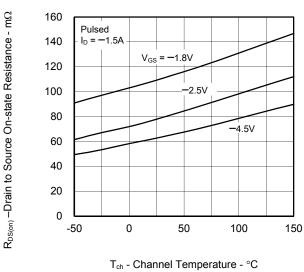


TE RESISTANCE vs. DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

| y_{fs} | - Forward Transfer Admittance - S

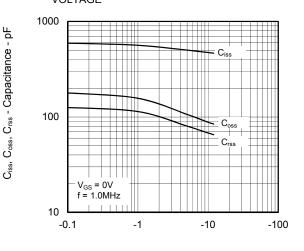
 $R_{\text{DS(on)}}$ - Drain to Source On-state Resistance - $m\Omega$





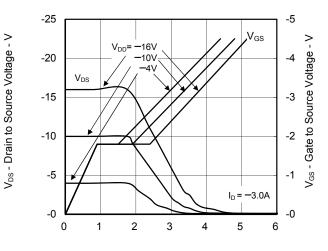
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



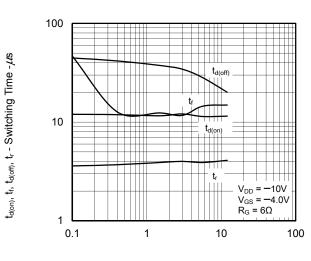
V_{DS} – Drain to Source Voltage - V

DYNAMIC INPUT/OUTPUT CHARACTERISTICS

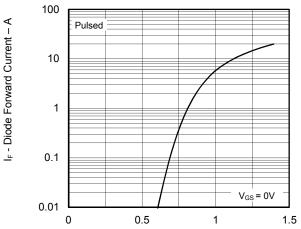


Q_G - Gate Charge - nC

SWITCHING CHARACTERISTICS



I_D - Drain Current - A



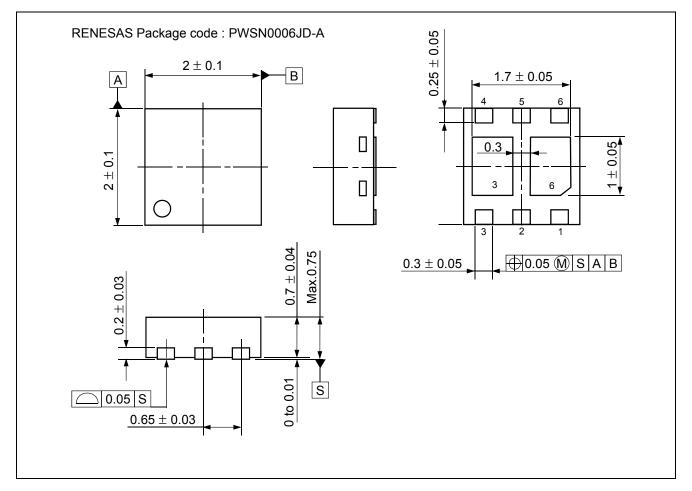
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



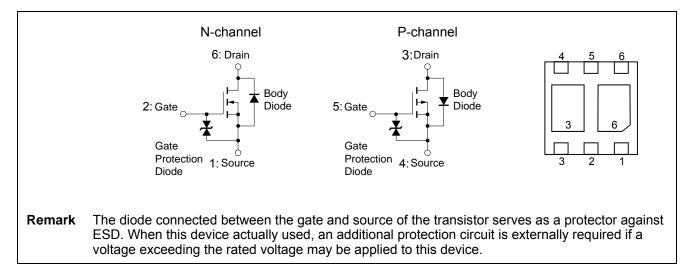
 $V_{\text{F(S-D)}}$ - Drain to Source Voltage - V

Package Drawings (Unit: mm)

6pinHUSON2020(DUAL)



Equivalent Circuit / Pin Assignment





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